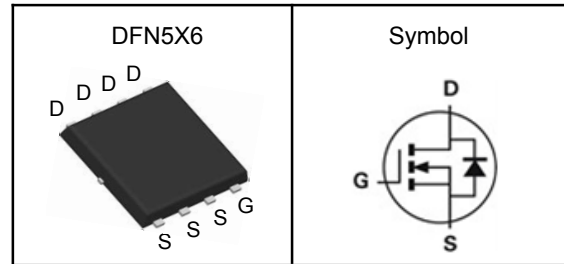


N-Channel Enhancement Mode MOSFET
Features

- Low Rdson for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description

Applications

- Power Management in Desktop Computer
- DC/DC Converters

V _{DSS}	30	V
R _{DS(ON)-Typ}	3	mΩ
I _D	96	A

Absolute Maximum Ratings (T_A=25°C, Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
V _{DSS}	Drain-Source Voltage	30	V
V _{GSS}	Gate-Source Voltage	±20	V
T _J	Maximum Junction Temperature	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
I _{DM} ^①	Pulse Drain Current Tested	T _C =25°C	384
I _D	Continuous Drain Current	T _C =25°C	96
		T _A =25°C	18
P _D	Maximum Power Dissipation	T _C =25°C	56.8
		T _A =25°C	1.95
E _{AS} ^②	Avalanche Energy, Single pulse L=0.1mH	192	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
R _{θJA} ^③	Thermal Resistance-Junction to Ambient	64	°C/W
R _{θJC}	Thermal Resistance-Junction to Case	2.2	°C/W

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



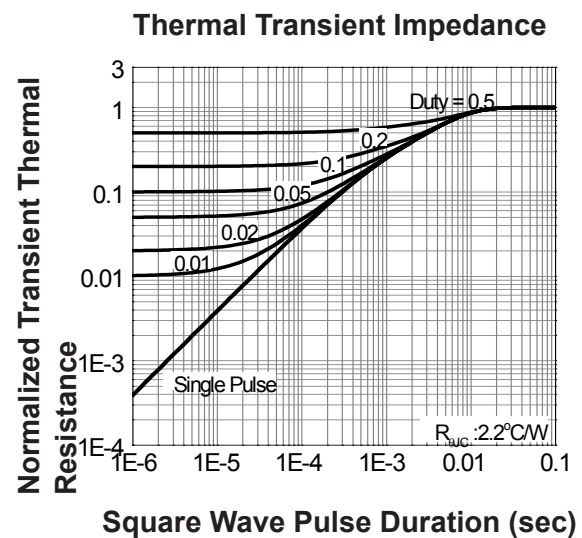
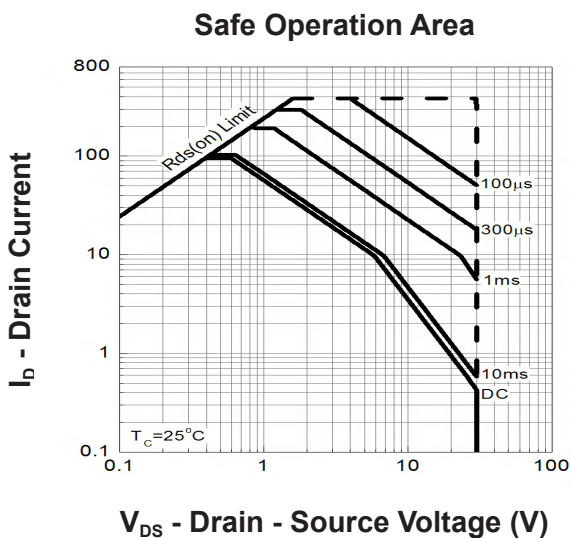
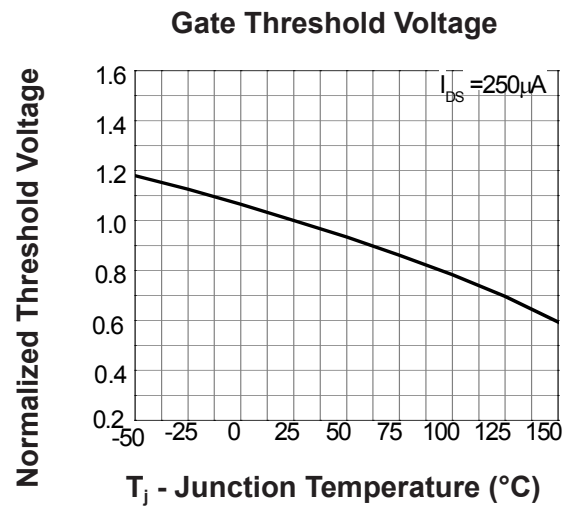
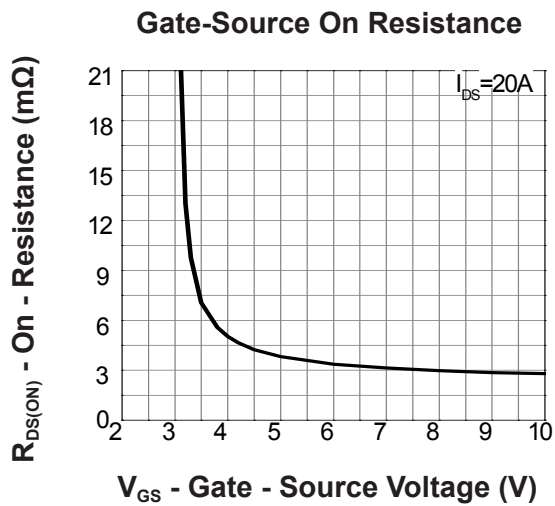
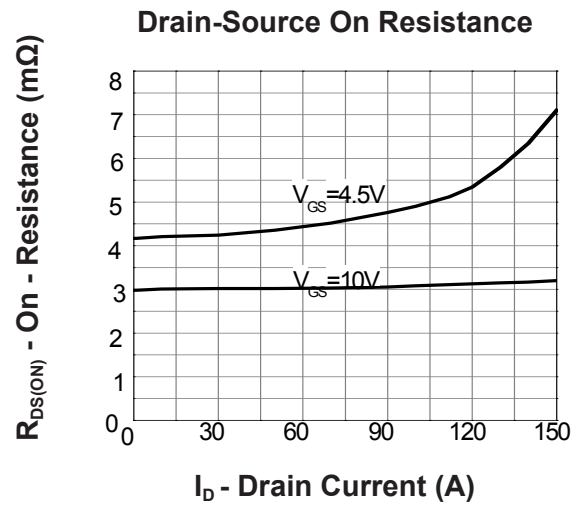
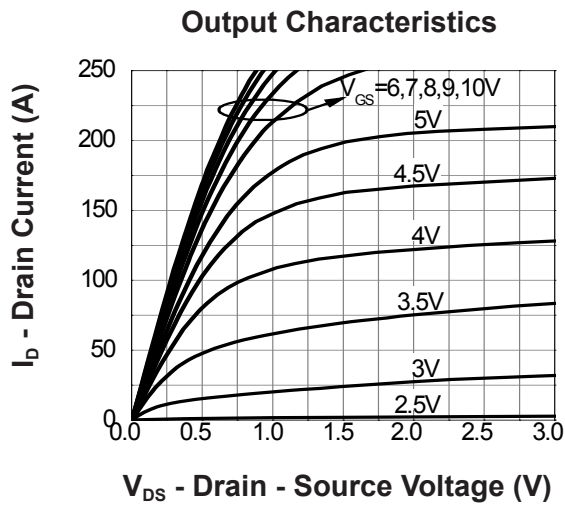
N-Channel Enhancement Mode MOSFET

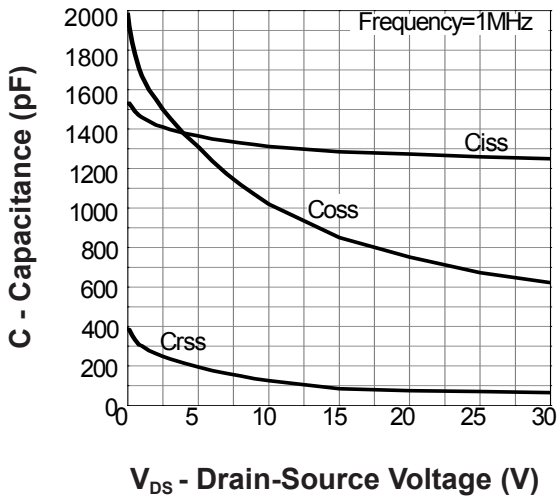
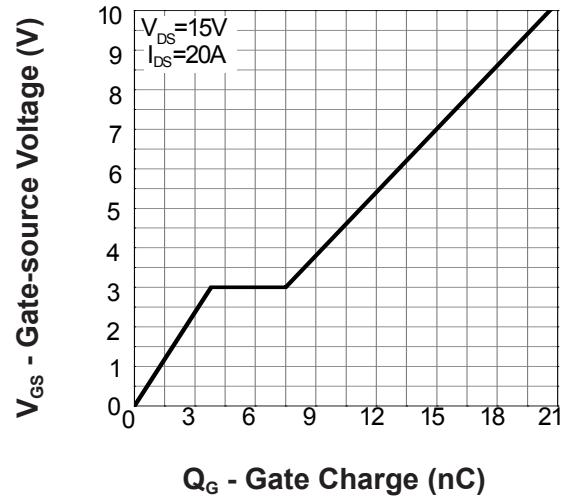
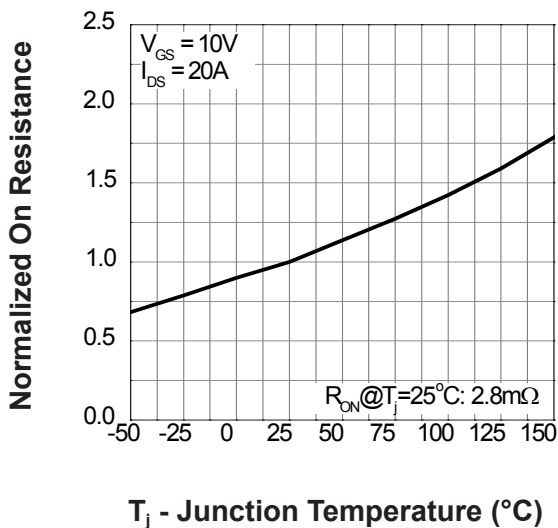
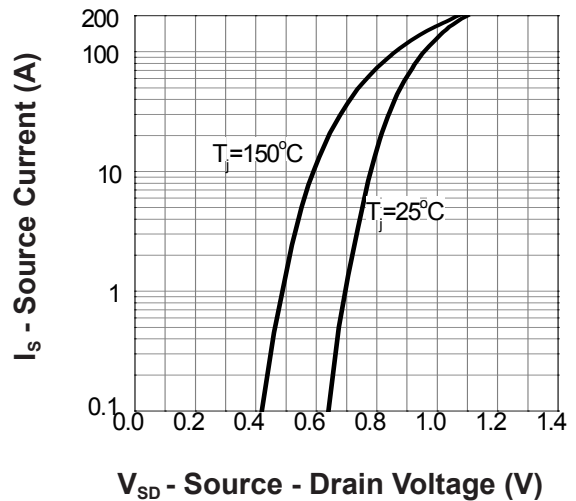
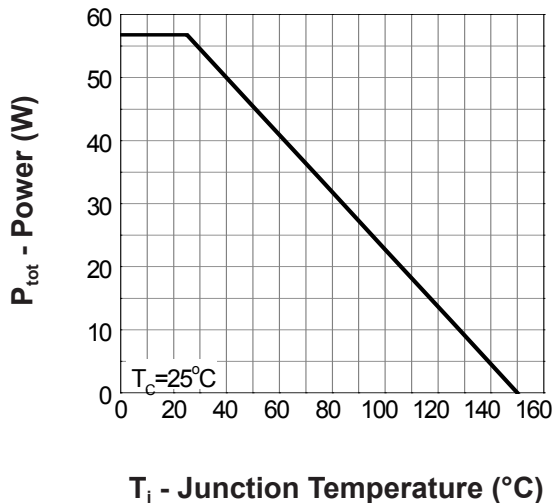
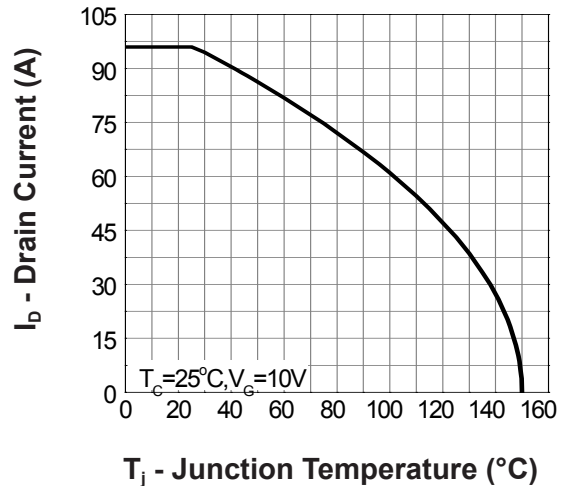
Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

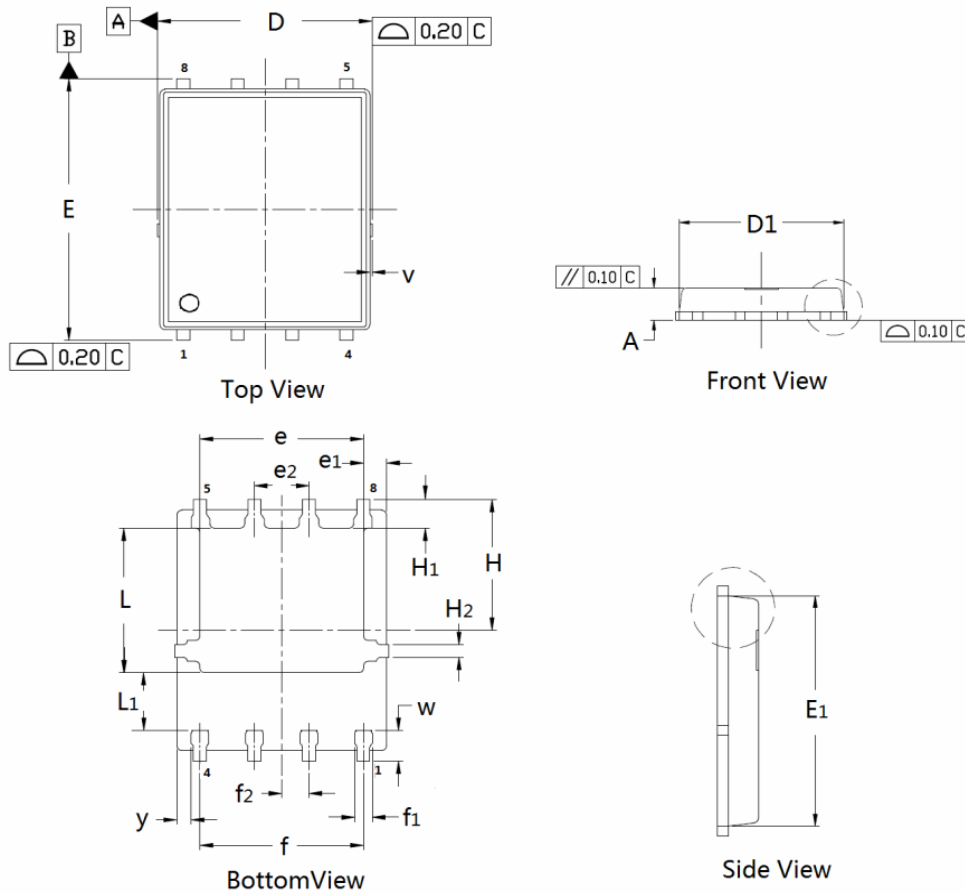
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	---	---	1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.3	---	2.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=20A$	---	3	3.8	m Ω
		$V_{GS}=4.5V, I_D=15A$	---	4.2	5.5	
gfs	Forward Transconductance	$V_{DS}=5V, I_D=10A$	---	24.6	---	S
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V, \text{Freq.}=1\text{MHz}$	---	1285	---	pF
C_{oss}	Output Capacitance		---	850	---	
C_{rss}	Reverse Transfer Capacitance		---	85	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=15\Omega, I_{DS}=1A, V_{GEN}=10V, R_G=6\Omega$	---	12.4	---	nS
T_r	Turn-on Rise Time		---	9.5	---	
$T_{d(off)}$	Turn-off Delay Time		---	27.2	---	
T_f	Turn-off Fall Time		---	35.2	---	
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=4.5V, I_D=20A$	---	9.8	---	nC
Q_{gs}	Gate-Source Charge		---	3.8	---	
Q_{gd}	Gate-Drain Charge		---	3.7	---	
Source-Drain Characteristics						
$V_{SD}^{④}$	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=20A, T_J=25^{\circ}\text{C}$	---	0.8	1.1	V
t_{rr}	Reverse Recovery Time	$I_{DS}=20A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	35.6	---	nS
Q_{rr}	Reverse Recovery Charge		---	26	---	nC

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤: Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET
Typical Characteristics


N-Channel Enhancement Mode MOSFET
Capacitance

Gate Charge

Drain-Source On Resistance

Source-Drain Diode Forward

Power Dissipation

Drain Current


N-Channel Enhancement Mode MOSFET
DFN5×6 Package Outline Data

DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D ₁	4.80	4.89	5.10	E	5.90	6.11	6.25
E ₁	5.65	5.74	5.95	e	3.72	3.80	3.92
e ₁	--	0.5	--	e ₂	--	1.	--
f	--	3.8	--	f ₁	0.31	0.37	0.51
f ₂	--	0.6	--	H	--	3.	--
H ₁	0.59	0.63	0.79	H ₂	0.26	0.28	0.32
L	3.35	3.45	3.65	L ₁	--	1.	--
v	--	0.1	--	w	0.64	0.68	0.84
y	--	0.3	--				